

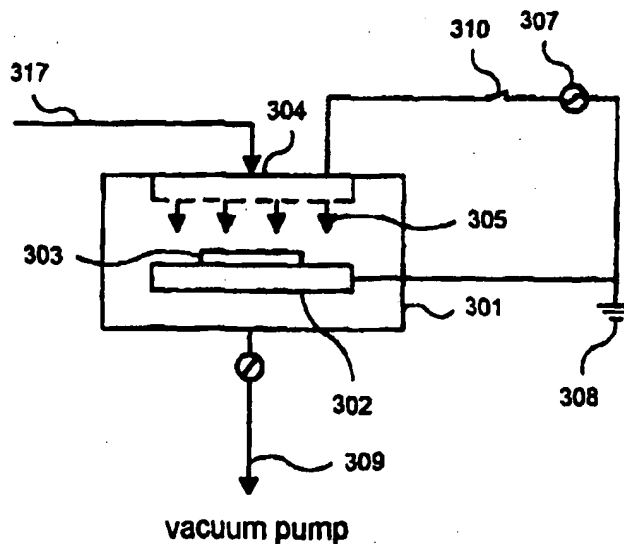


## INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

<b>(51) International Patent Classification <sup>7</sup> :</b>  <b>H01L 21/205</b>	<b>A1</b>	<b>(11) International Publication Number:</b> <b>WO 00/63957</b>  <b>(43) International Publication Date:</b> 26 October 2000 (26.10.00)
<b>(21) International Application Number:</b> PCT/KR00/00310 <b>(22) International Filing Date:</b> 6 April 2000 (06.04.00)  <b>(30) Priority Data:</b> 1999/11877      6 April 1999 (06.04.99)      KR  <b>(71) Applicant (for all designated States except US):</b> GENITECH, INC. [KR/KR]; 1694-5 Sinil-dong, Taedok-ku, Taejon 306-230 (KR).  <b>(72) Inventors; and</b> <b>(75) Inventors/Applicants (for US only):</b> LEE, Chun-Soo [KR/KR]; 109-202 Hanbit Apt., 99 Uheun-dong, Yusong-gu, Taejon 305-333 (KR); KANG, Won-Gu [KR/KR]; 118-908 Hanbit Apt., 99 Uheun-dong, Yusong-gu, Taejon 305-333 (KR). LEE, Kyu-Hong [KR/KR]; 105-606 Hanul Apt., 160-1 Shinsung-dong, Yusong-gu, Taejon 305-345 (KR). YI, Kyoung-Soo [KR/KR]; 118-1506 Hanbit Apt., 99 Uheun-dong, Yusong-gu, Taejon 305-333 (KR).  <b>(74) Agent:</b> HUH, Jin-Seok; J.S. Huh Patent Office, 206 Sungji Building, 1338-22 Seocho-dong, Seocho-ku, Seoul 137-070 (KR).		<b>(81) Designated States:</b> JP, US, European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE).  <b>Published</b> <i>With international search report.</i> <i>In English translation (filed in Korean).</i>

**(54) Title:** METHOD OF FORMING A THIN FILM**(57) Abstract**

The invention provides a method of forming a thin film for semiconductor or flat panel display devices. In a chemical vapor deposition method which supplies cyclically reactant gases and a purge gas which prevents the gas-phase reaction between the reactant gases, generating plasma on a substrate synchronously with the gas supply cycle can form a thin film at low temperature and reduce particle generation at exhaust.



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## METHOD OF FORMING A THIN FILM

### TECHNICAL FIELD

The present invention relates to a deposition method of thin films required  
5 for manufacturing semiconductor devices, flat panel devices, and etc..

### BACKGROUND ART

Such thin films may include metal films, insulator films such as metal oxide  
films, metal nitride films and etc., films for capacitors, interconnects and electrodes,  
10 inorganic films used for diffusion prevention, and etc.

These thin films may be formed by a physical vapor deposition, for example  
a sputtering process. The sputtering process, however, forms thin films with poor step  
coverage, so a chemical vapor deposition method is usually employed to improve the  
step coverage.

15 One of the most common chemical vapor depositions of the prior art is  
carried out by an apparatus as shown in FIG. 1A. Referring to FIG. 1A, process gases  
or other reactants 11, 12, 13 are supplied into a reactor 1, respectively, through mass  
flow controllers 21, 22, 23 and valves 30, 31, 32. In this case, a shower head 4 is  
utilized to obtain uniform flow 5 of the process gases. When a source material is  
20 liquid or solid having low equilibrium vapor pressures, a vaporizer 16 is also  
employed that can heat the source material in a suitable temperature to vaporize and  
can supply the vaporized source material into the reactor 1 with the carrier gas 13.  
When the vaporizer is employed, the initial portion of the source material carried by  
the carrier gas 13 is exhausted via a bypass valve 33 and an outlet tube 18 due to the  
25 fluctuation of flow rate and source material concentration. Then, the bypass valve 33  
is shut off and a valve 32 connected to a central supplying tube 17 is opened to supply  
the carrier gas into the reactor 1.

The chemical vapor deposition of the prior art performed in this apparatus  
has the following features: At first, all process gases 11, 12, 13 required for the  
30 deposition are supplied into the reactor 1 at the same time so that the film is  
continuously deposited during the process times 11', 12', 13' as in an example shown  
in FIG. 1B. At second, the shower head 4 is usually employed to make uniform flow

5 of the process gases on the surface of a substrate.

This method has the following disadvantages: At first, since all process gases exist within the reactor at the same time, the process gases may react in gas phase thereby can deteriorate step coverage of the deposited film and/or produce particles which contaminate the reactor. At second, when using a metal-organic compound as a source material, it is difficult to deposit the film that does not contain carbon impurities. At third, in the case of depositing a multi-component film, all the reactant materials must react simultaneously while the supply of each reactant material is controlled separately by mass flow of the carrier gas, so it is very difficult to control the composition of the deposited film precisely.

To overcome the foregoing problems, a method is proposed in which the process gases are supplied separately as time-divisional pulses rather than supplied continuously.

An example of supplying process gases in this deposition method is shown in FIG. 2A. Valves in a gas introducing part can be opened or closed so that the process gases can be supplied cyclically as time-divisional pulses into the reactor without being mixed with each other.

Referring to FIG. 2A, it can be seen that the process gases 11, 12, 13 in FIG. 1A are supplied in a cycle  $T_{\text{cycle}}$  of 13', 12', 11' and 12'. A film can be deposited by repeating this cycle. In general, purge gas 12 is supplied between the supply pulses of the reactants 11 and 13 so that the remaining reactants are removed from the reactor before the next reactant is supplied.

Hereinafter, a time-divisional deposition mechanism will be described. Chemical adsorption temperatures of the reactants onto the substrate are generally lower than thermal decomposition temperatures of the reactants. Therefore, when a deposition temperature is maintained higher than the chemical adsorption temperature of the reactant onto the substrate and lower than the thermal decomposition temperature of the reactant, the reactant supplied into the reactor only adsorbs chemically onto the surface of the substrate rather than decomposes. Then, the remaining reactant is exhausted out of the reactor by the purge gas supplied into the reactor. After that, another reactant is introduced into the reactor to react with the reactant adsorbed on the surface, and thus form a film. Because the reactant adsorbed

on the substrate cannot form more than one molecular layer, film thickness formed in one supply cycle  $T_{\text{cycle}}$  is constant regardless of amount or time of the supplied reactants. Therefore, as shown in FIG. 2B, the deposited film thickness is saturated as the supplying time elapses. In this case, the deposited film thickness is controlled  
5 only by the number of the repeated supply cycles.

In the other hand, when the deposition process temperature is no lower than the thermal decomposition temperature of the reactants, the deposited film thickness is proportional to the supply time of the reactants in the supply cycle because the reactants introduced into the reactor decompose continuously to form films on the  
10 substrate. In this case, deposited film thickness according to the supply time of the reactants is shown in FIG. 2C.

However, the foregoing time-divisional deposition has problems as follows:

At first, the reactants used in the deposition process must react readily. Otherwise it is difficult to form a film by time-divisional deposition. In this case, a  
15 method is required that facilitate the chemical reaction even at low temperatures.

At second, the exhausting part of the apparatus may be contaminated with particles due to the reactions between the reactants. The gas-introducing part and the reactor may not be contaminated with the particles due to the reactions of the reactants because the reactants are separated by the purge gas. In the other hand, the  
20 exhausting part may be easily contaminated with particles because the reactants mix and react with each other at exhaust.

At third, it is required to supply inert purge gas between the reactant supply pulses to prevent gas-phase reactions in the gas-introducing part and the reactor, so the gas-supply cycle is complex, the time for a supply cycle is longer than absolutely  
25 necessary, and thus the deposition is slow.

A method is disclosed in the US Patent No. 5,916,365 in which a film is formed by repeating a gas-supply cycle, i.e., supplying first reactant gas into a reactor, exhausting remaining reactant gas within the reactor by a vacuum pump, supplying second reactant gas which is activated by passing through a radical generator using an  
30 RF power or other means, and exhausting remaining reactant gas by the vacuum pump.

The exhaust rate of the vacuum pump decreases as the pressure decreases, so

it takes long time to exhaust the remaining reactant gases from the reactor with the vacuum pump. Therefore, in this method, it is difficult to have high growth rate of the film per unit time when it desired to exhaust the remaining reactant gases completely. When the exhausting time is too short, the reactant gases remain in the reactor so that  
5 the two reactant gases mix and react in gas phase. Furthermore, in the method of the US Patent No. 5,916,365, it is difficult to maintain stable plasma in the reactor because the supply and exhaust of the reactant gases cause wide pressure variation in the reactor.

10

### DISCLOSURE OF INVENTION

Therefore, it is an object of the present invention to provide a method which can form a thin film effectively even if reactants do not react readily in a time-divisional source supply chemical vapor deposition method.

It is another object of the present invention to provide a method which can  
15 minimize supply time of a purge gas in a gas-supplying cycle to reduce cycle time in a time-divisional source supply chemical vapor deposition.

It is further object of the present invention to provide a method which can reduce particle contamination of the apparatus at the exhausting part of an apparatus for time-divisional source supply chemical vapor deposition.

20 In order to realize those foregoing objects, the present invention provides a method used for a chemical vapor deposition in which source gases for forming a thin film are supplied into a reactor in a time-divisional manner so that they may not be mixed with each other in the reactor. In the method of the invention, the process gases are activated into plasma to facilitate the film formation, wherein plasma is  
25 generated synchronously with gas supply cycle.

For more clear description, process gases are classified as three kinds:

At first, the process gas that thermally decomposes to form a solid film is called a deposition gas. The deposition gas includes, for example, titanium-organic compound used for chemical vapor deposition for forming a TiN film.

30 At second, the process gas that does not decompose by itself or does not form a solid film upon self-decomposition, however, forms a solid film when reacts with a deposition gas is called a reactant gas. The reactant gas includes, for example,

ammonia used in a chemical vapor deposition process for forming a nitride film, and oxygen gas used in a chemical vapor deposition process for forming an oxide film.

At third, the other inert process gas that is supplied between the supplies of the deposition gas and the reactant gas to separate the deposition gas and the reactant gas is called a purge gas. In general, helium, argon, nitrogen gas and etc. are used for a purge gas. Those gases contain the constituent element of the film may also be used for a purge gas if they do not react with a deposition gas. In this case, the purge gas can be used for a reactant gas when activated by plasma.

Therefore, one of the most evident features of the present invention, in a chemical vapor deposition which forms a film on a substrate by supplying process gases which include a deposition gas, a reactant gas, and a purge gas into a reactor by repeating cycles of time-divisional gas supply, is to provide a method of generating plasma on the substrate synchronously with the supply cycles to activate at least one of the process gases. In this case, the plasma is generated synchronously with the supply cycle of the reactant gas.

Also, when a purge gas contains constituent elements of a film material and a reactant gas contains the other constituent elements of the film material and the purge gas does not substantially react with the reactant gas, plasma may be preferably generated synchronously during the supply cycle of the purge gas.

In the other hand, a film is deposited by alternate supply of only a deposition gas and a purge gas without any reactant gas into a reactor. In this case, the purge gas preferably contains constituent elements of a film material and does not react substantially with the deposition gas if not activated; wherein plasma is preferably generated synchronously at least in part during the supply cycle of the purge gas to facilitate the reaction of the purge gas with the deposition gas.

The films deposited by above methods may be heat-treated after the deposition.

#### BRIEF DESCRIPTION OF DRAWINGS

FIG. 1A and FIG. 1B are drawings showing an apparatus for a chemical vapor deposition and a method of supplying reactant gases employed in a film deposition process of the prior art;

FIG. 2A to FIG. 2C are graphs showing a deposition process of the prior art which supply reactant gases in a time-divisional manner;

FIG. 3A to FIG. 3C are a schematic view of an apparatus to be employed to the present invention and graphs for illustrating a gas supplying method, respectively;  
5 and

FIG. 4A to FIG. 4C are drawings showing processes for forming a multi-component film by using the method of the present invention.

### BEST MODE FOR CARRYING OUT THE INVENTION

10 Preferred embodiments of the present invention will be described hereinafter in reference to the appended drawings:

FIG. 3A is a schematic view of an apparatus to be employed to the present invention.

Referring to FIG. 3A, the apparatus is same as that of FIG. 1A, except that a  
15 plasma generator is attached thereto. RF(radio frequency) power is applied into a reactor 301 via an RF power supply 307 which is connected to a gas shower head 304 and a susceptor 302 so that plasma can be generated on a substrate 303. When RF power from the RF power supply 307 is cyclically applied into the reactor by turning on and off a switch 310 with the supply cycle of gases, plasma can be synchronously  
20 generated with the gas supply cycle. Gases are supplied through a supply tube 317, and the shower head 304 is adapted for the purpose of obtaining uniform flow 305 of process gases on the surface of the substrate 303 as in the prior art.

First embodiment of the present invention which is carried out by the apparatus shown in FIG. 3A will be described in reference to the graphs in FIG. 3B  
25 and FIG. 3C.

FIG. 3B is a graph showing that the process gases are supplied into the reactor in the supply cycle of deposition gas 13', purge gas 12', reactant gas 11' and  
30 purge gas 12'. At first, the deposition gas 13' is supplied into the reactor to be adsorbed to the substrate, and then the purge gas 12 is supplied to remove the remaining deposition gas from the reactor. Then, the reactant gas 11' is supplied into the reactor and at the same time the switch 310 is closed to activate the reactant gas 11' with plasma, and thus facilitate chemical reaction with the deposition gas 13'



adsorbed onto the substrate. When supply of the reactant gas is interrupted, the switch 310 is opened to stop plasma generation and the purge gas 12' is introduced to remove the remaining reactant gas. In this method, the film can be formed even if the reaction between the deposition gas 13' and reactant gas 11 is weak because the reactant gas 11 is activated with plasma.

For example, when a metal-organic compound is used as chemical vapor deposition source, plasma-activated reactant gas may accelerate decomposition of the metal-organic compound and reduce carbon contamination of the film. Also, the activation energy applied to the film by the plasma may enhance crystalization, physical characteristics and electrical characteristics of the film.

As a detailed example of this process, a copper compound may be reduced to form a metallic copper film. In the temperature no higher than thermal decomposition temperature of the deposition gas, chemical reaction between the deposition gas and hydrogen gas, i.e. the reactant gas, does not take place and thus a metallic copper film cannot be formed. Therefore, a plasma generator as shown in FIG. 3A is installed, and plasma is generated as hydrogen gas is supplied into the reactor so that chemical reaction between the hydrogen gas and the copper source adsorbed to the substrate surface may be accelerated and thus form a metallic copper film. If the plasma generator is powered on while supplying the deposition gas, the copper source may decompose in gas phase so that particle contamination or poor step coverage may take place. Therefore, it is advantageous to synchronize RF power applied to the plasma generator with the supply cycle in such a manner that the plasma generator is powered off when the deposition gas is supplied and on only when the reactant gas is supplied.

According to second embodiment of the present invention, a gas that may undergo a very weak chemical reaction with the deposition gas, if any, may be employed as a reactant gas or a purge gas, in condition that this gas contains constituent elements of the film. A gas supplying method like this is shown in FIG. 3C. In this method, the deposition gas 13' is primarily adsorbed to the substrate, the remaining deposition gas is removed by the purge gas 12' which undergoes almost no chemical reaction with the deposition gas, if any, but may include constituent elements of the film, and then the plasma generator is powered on to transform the

purge gas 12' into the reactant gas 15'. This reactant gas 15' can form a film by reacting with the deposition gas absorbed to the substrate. Then, after the plasma generator is powered off to stop the reaction, the deposition gas 13' can be supplied again into the reactor without any concerns about gaseous reaction. Therefore, during  
5 purge gas supply in the gas supply cycle, the plasma power supply is switched in the order of off, on, and off, thereby is equivalent of supplying a purge gas, a reactant gas and a purge gas, respectively. Also, the concentration of the activated species decreases very rapidly after the plasma power is turned off, so supply time of the purge gas can be minimized after the plasma power is off. In this kind of gas supply  
10 cycle, the gas-supply cycle consists of turn-on and turn-off of plasma generator instead of the supply of different gases. This method permits the time-divisional chemical vapor deposition with only two kinds of gases, so the gas supplying part of an apparatus can be simple and the cycle time of gas supply can be reduced. Furthermore, the deposition gas and the purge gas do not react with each other even if  
15 mixed, so there is no concerns about the particle contamination in the exhausting part.

Both of the foregoing two embodiments can be employed for the deposition of TiN film which is used for diffusion barrier as well as adhesive and anti-reflectory coatings.

Using the first embodiment, a TiN film may be formed by repeating the  
20 cycle of the supply of Ti-organic source for a deposition gas, ammonia gas for a reactant gas, and nitrogen gas for a purge gas, in which plasma is generated when the reactant gas is supplied.

When employing the second embodiment, Ti-organic source is used for a deposition gas, nitrogen gas for a purge gas, respectively, in which the plasma  
25 generator is powered on thereby causing the absorbed deposition gas to react with nitrogen gas after the deposition gas is removed by nitrogen gas. A TiN film may be formed by repeating the cycle including these steps. In this case, the nitrogen purge gas never reacts with the deposition gas when the plasma power supply is off so that particle is not generated at all.

30 FIG. 4A to FIG. 4C are drawings showing steps of forming a multi-component film by employing a method of the present invention.

FIG. 4A illustrates a process of forming a single-component film 62 on the

substrate 66 by a simple process cycle. For example, a metal-organic source is chemisorbed to the substrate, and a reactant gas is supplied with plasma power turned on, and thus a film 62 is formed which contains the metal element contained in the metal-organic source.

5        FIG. 4B shows that the process of FIG. 4A is repeatedly applied to form different layers 62 and 63. Herein, a film is formed with a desired thickness and composition by alternatively forming layers 62, 63 with different composition which may contain different elements. The layers 62 and 63 can be as thin as an atomic layer, so the deposited film is sufficiently homogeneous, which may be transformed  
10    to thermodynamically more stable phase 65 after thermal treatment.

### INDUSTRIAL APPLICABILITY

In the method of the present invention, a chemical vapor deposition of supplying process gases in a time-divisional manner is adapted with an idea of  
15    generating plasma synchronously with source supply cycle. Therefore, this method can be effectively applied for forming films which include metal components such as metal films, metal oxide films and metal nitride films which are used for semiconductor and flat panel display devices.

Herein above the invention has been described in reference to the preferred  
20    embodiments, but various other modifications and variations will be apparent to those skilled in the art without departing from the scope and spirit of the present invention.

**WHAT IS CLAIMED IS :**

1. A method of forming a thin film on a substrate by a chemical vapor deposition in which process gases are supplied into a reactor by repeating a cycle of time-divisional combination;

5        wherein said process gases include a deposition gas which forms a film when thermally decomposed but does not decompose thermally at the process temperature, a reactant gas which does not thermally decompose spontaneously at the process temperature or does not form a film upon thermal self-decomposition, and a purge gas for preventing chemical reaction between said deposition gas and said reactant gas;  
10      and

         wherein plasma is generated on said substrate synchronously with at least one supply of said process gases in the cycle.

2. The method of forming a thin film according to claim 1, wherein plasma is  
15      generated synchronously with the supply of said reactant gases.

3. The method of forming a thin film according to claim 1, wherein said  
purge gas contains constituent elements of the film material and said reactant gas contains other constituent elements of the film material, respectively; wherein said  
20      purge gas does not react substantially with said reactant gas; and wherein said plasma is generated synchronously with the supply of said purge gas.

4. The method of forming a thin film according to claim 1, wherein said thin  
film is heat-treated after deposition.

25        5. A method of forming a thin film on a substrate in a chemical vapor deposition in which process gases are supplied into a reactor by repeating a cycle of time-divisional combination;

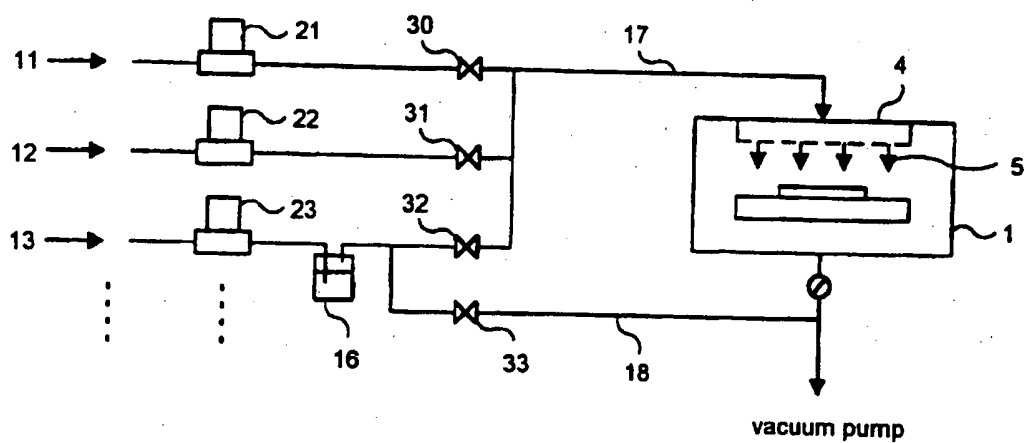
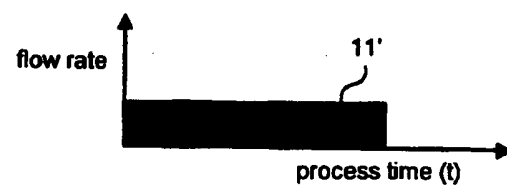
         wherein said process gases include a deposition gas which forms a film when  
30      thermally decomposed but does not decompose thermally at the process temperature, and a purge gas for exhausting said deposition gas from a reactor;

         wherein said purge gas contains constituent elements of the film material and

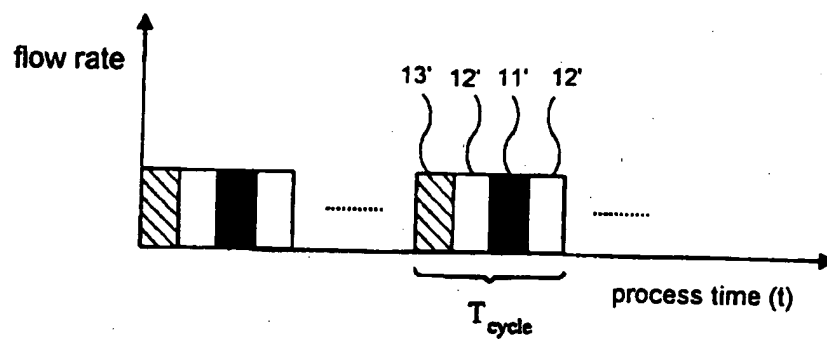
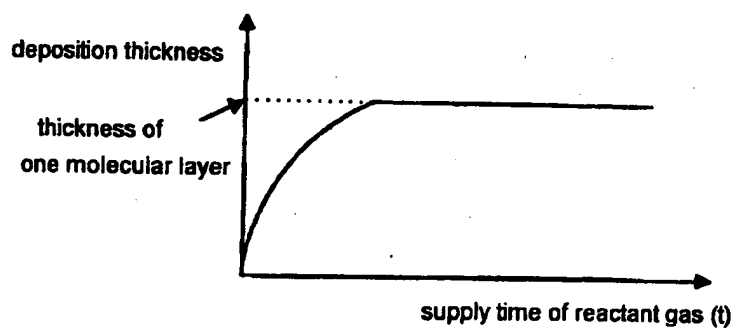
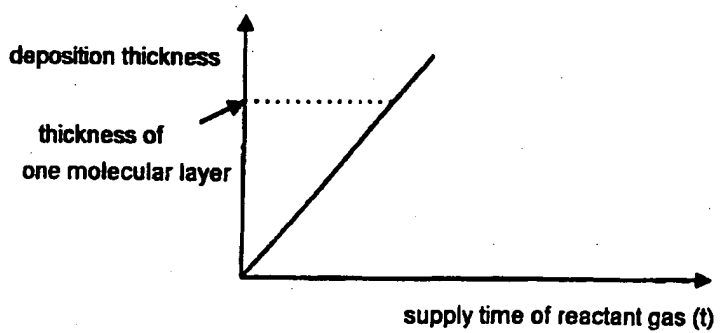
substantially does not react with said deposition gas in non-activated state; and  
wherein plasma is generated synchronously at least in part with the supply of  
said purge gas causing said purge gas to react with said deposition gas.

- 5           6. The method of forming a thin film according to claim 5, wherein said thin  
film is heat-treated after deposition.

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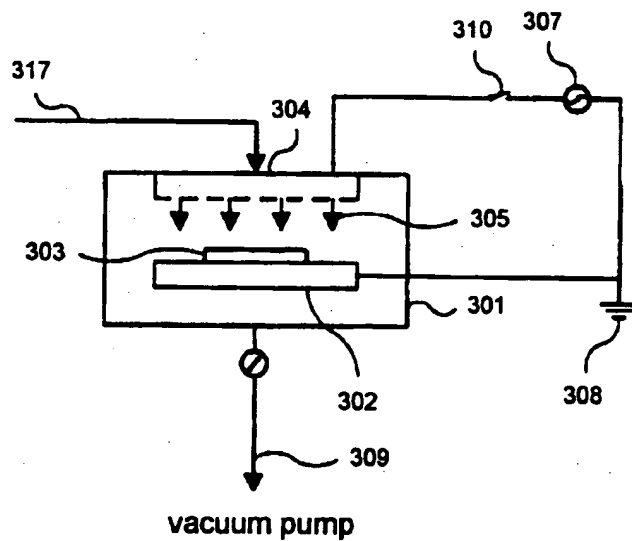
**FIG. 1A****FIG. 1B**

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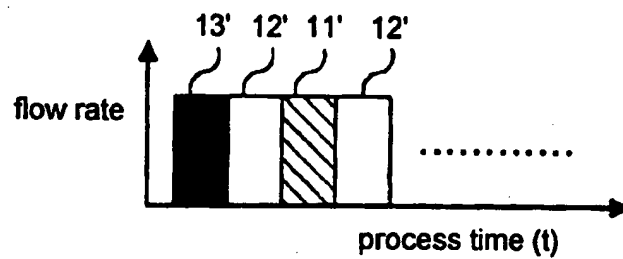
**FIG. 2A****FIG. 2B****FIG. 2C**

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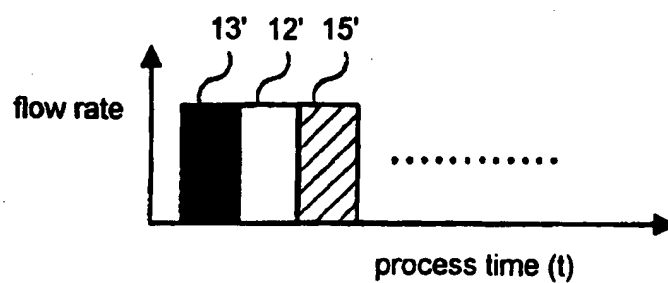
**FIG. 3A**



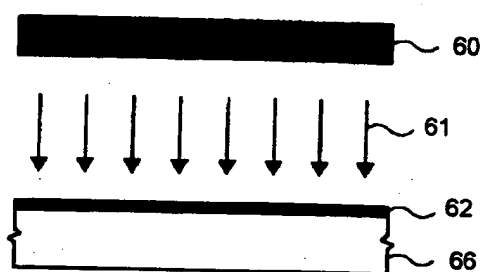
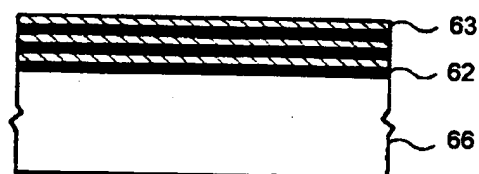
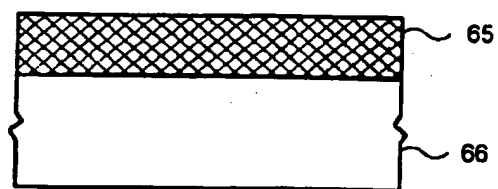
**FIG. 3B**



**FIG. 3C**





**FIG. 4A****FIG. 4B****FIG. 4C**

## INTERNATIONAL SEARCH REPORT

International application No.

PCT/KR00/00310

**A. CLASSIFICATION OF SUBJECT MATTER****IPC7 H01L 21/205**

According to International Patent Classification (IPC) or to both national classification and IPC

**B. FIELDS SEARCHED**

Minimum documentation searched (classification system followed by classification symbols)

IPC7 H01L 21/205, IPC7 H01L 21/20

Documentation searched other than minimum documentation to the extent that such documents are included in the files searched

Korean Patents and applications for inventions since 1975

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Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

KIPONET

**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	JP 06-291048 B1 (NISSAN ELECTRIC CO. LTD) 18.October.1994 (18.10.1994) page1, lines 1-10 claims 1 page 2, column 2, lines 38 - page3, column 1, lines 13 Fig. 1, Fig. 2	1-3
A	JP 03-048421 A (TOKYO ELECTRON LTD) 01. March.1991(01.03.1991) claims 1,2	1-3

☐ Further documents are listed in the continuation of Box C.☒ See patent family annex.

* Special categories of cited documents:	"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention
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**INTERNATIONAL SEARCH REPORT**

Information on patent family members

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Patent document cited in search report	Publication date	Patent family member(s)	Publication date
JP 06291048 B1	18.10.1994	JP 2646941 JP 6291048	27.08.1997 18.10.1994

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